

IN THE CLAIMS:

1 1. (currently amended) A die containing package comprising:
2 | a die defining electrical die contacts, the die contacts arranged along a first and an
3 | opposite side of the die,
4 | a substrate defining first substrate contacts,
5 | flattened electrical conductive balls attached to the die contacts and making electri-
6 | cal connection thereto,
7 | electrical conductive runs on the substrate that run substantially under the die con-
8 | necting the first substrate contacts, wherein the first substrate contacts are located adjacent
9 | to the first side of the die, to second substrate contacts, wherein the second substrate con-
10 | tacts are located ~~on the substrate~~ adjacent to the opposite side of the die, ~~the first substrate~~
11 | ~~contacts,~~
12 | electrically conductive wires with first ends making electrical connections to the
13 | first substrate contacts, wherein the wires are formed to run substantially parallel to the
14 | surface of the die, and wherein the other ends are horizontally attached to the flattened
15 | balls.

1 2-3. canceled.

1 4. (previously presented) The die containing package of claim 1 wherein the second sub-
2 | strate contacts are located on the substrate to accommodate a pin out different from the die.

1 5. (currently amended) A process for packaging a die comprising the steps of:
2 | defining electrical die contacts, the electrical die contacts arranged along a first and
3 | an opposite side of the die,
4 | defining a substrate with first substrate contacts,

5 flattening electrical conductive balls,
6 attaching the flattened electrically conductive balls to the die contacts,
7 forming electrical conductive runs on the substrate that run substantially under the
8 die connecting the first substrate contacts, wherein the first substrate contacts are located
9 adjacent to the first side of the die, to second substrate contacts, wherein the second sub-
10 strate contacts are located ~~on the substrate~~ adjacent to the opposite side of the die, ~~the first~~
11 ~~substrate contacts,~~
12 connecting electrically conductive wires to the first substrate contacts,
13 running the electrically conductive wires substantially parallel to the surface of the
14 die to the die contacts, and
15 horizontally attaching the other ends of the wires to the flattened electrical conductive balls
16 thereby making electrical connections therebetween, and wherein the other ends remain
17 substantially parallel to the surface of the die .

1 6-7. canceled.

1 8. (previously presented) The process of claim 5 further comprising the step of locating
2 the second substrate contacts on the substrate to accommodate a pin out different from the
3 die.